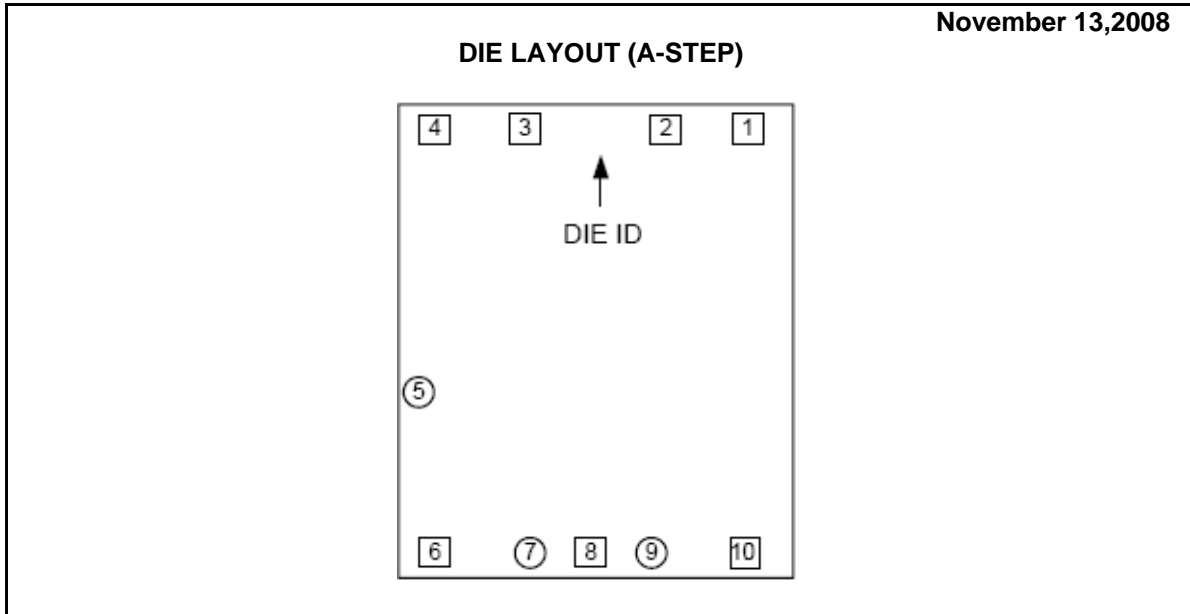


**LM95172QA2 MDA
13-BIT TO 16-BIT DIGITAL TEMPERATURE SENSOR WITH 3-WIRE INTERFACE**



DIE/WAFER CHARACTERISTICS

| Fabrication Attributes | | General Die Information | |
|-----------------------------|--|-----------------------------|-----------------|
| Physical Die Identification | LM95172A | Bond Pad Opening Size (min) | 69µm x 69µm |
| Die Step | A | Bond Pad Metalization | Al_ 0.5%Cu |
| Physical Attributes | | Passivation | PECVDOX+NITRIDE |
| Wafer Diameter | 200mm | Back Side Metal | BARE BACK |
| Die Size (Drawn) | 1143µm x 1607µm 45.0mils x 63.3mils | Back Side Connection | GND |
| Thickness | 254µm Nominal | | |
| Min Pitch | 255µm Nominal | | |

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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| Die Bond Pad Coordinate Locations (A -Step) | | | | | | |
|---|--------|----------------|---------|----------|---|----|
| (Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used | | | | | | |
| SIGNAL | PAD# | XY COORDINATES | | PAD SIZE | | |
| NAME | NUMBER | X | Y | X | Y | |
| Vdd Analog | 1 | 497.75 | 728.80 | 69 | x | 69 |
| Vdd IO | 2 | 242.80 | 728.80 | 69 | x | 69 |
| <u>OVERTEMP</u> | 3 | -147.35 | 728.80 | 69 | x | 69 |
| SC | 4 | -497.75 | 728.80 | 69 | x | 69 |
| NC | 5 | - | - | - | - | - |
| <u>CS</u> | 6 | -497.75 | -728.80 | 69 | x | 69 |
| NC | 7 | - | - | - | - | - |
| GND | 8 | 0.00 | -728.80 | 69 | x | 69 |
| NC | 9 | - | - | - | - | - |
| SI/O | 10 | 497.65 | -728.80 | 69 | x | 69 |

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Notes

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